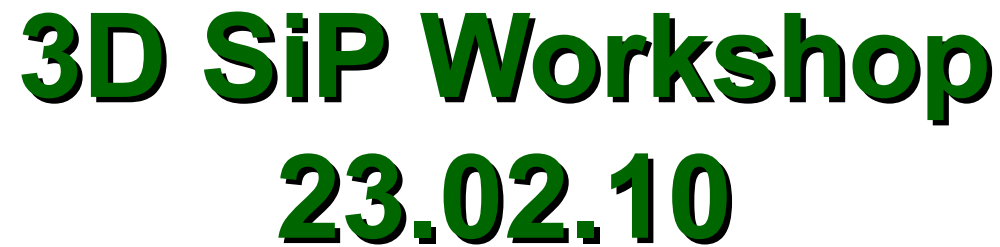


The logo for HDP (High Density Packaging) is displayed in a blue, serif font. It is positioned above a white rectangular box that contains the text 'USER GROUP INTERNATIONAL, INC.®' in a blue, sans-serif font. The entire logo is set against a light blue background that has a decorative, elongated shape.

**HDP**

**USER GROUP  
INTERNATIONAL, INC.®**

The main title of the workshop is '3D SiP Workshop' followed by the date '23.02.10'. The text is rendered in a large, bold, green, sans-serif font. It is centered on the page. To the left of the text, there is a vertical strip showing a close-up of a blue printed circuit board (PCB) with various components and labels like R30, R29, R45, C29, R53, R52, C33, R60, and R61.

# **3D SiP Workshop**

## **23.02.10**

**Santa Clara, CA**

**Paul Collander  
HDPUG Facilitator**

Santa Clara on Tuesday February 23 at 9 to 12 am

- Introduction to the planning process by Paul Collander, HDPUG Facilitator
- Introduction to the topic area to be covered by Chris Katzko, project leader, Meadville
- Company views by two invited member company representatives Bernd Appelt, ASE and others
- Statistical results from the Questionnaire
- List of identified issues suitable for technology assessment, demonstrations and/or reliability assessment
- Discussion on priorities in this list
- Brainstorming for additional issues to be worked on
- Formulate maximum 5 project ideas based on discussion so far: Technical coverage & Goals & Volunteers
- Voting on these 5 ideas, 1 or 2 to be flashed at Member Meeting next day
- How to proceed? Formation of top teams

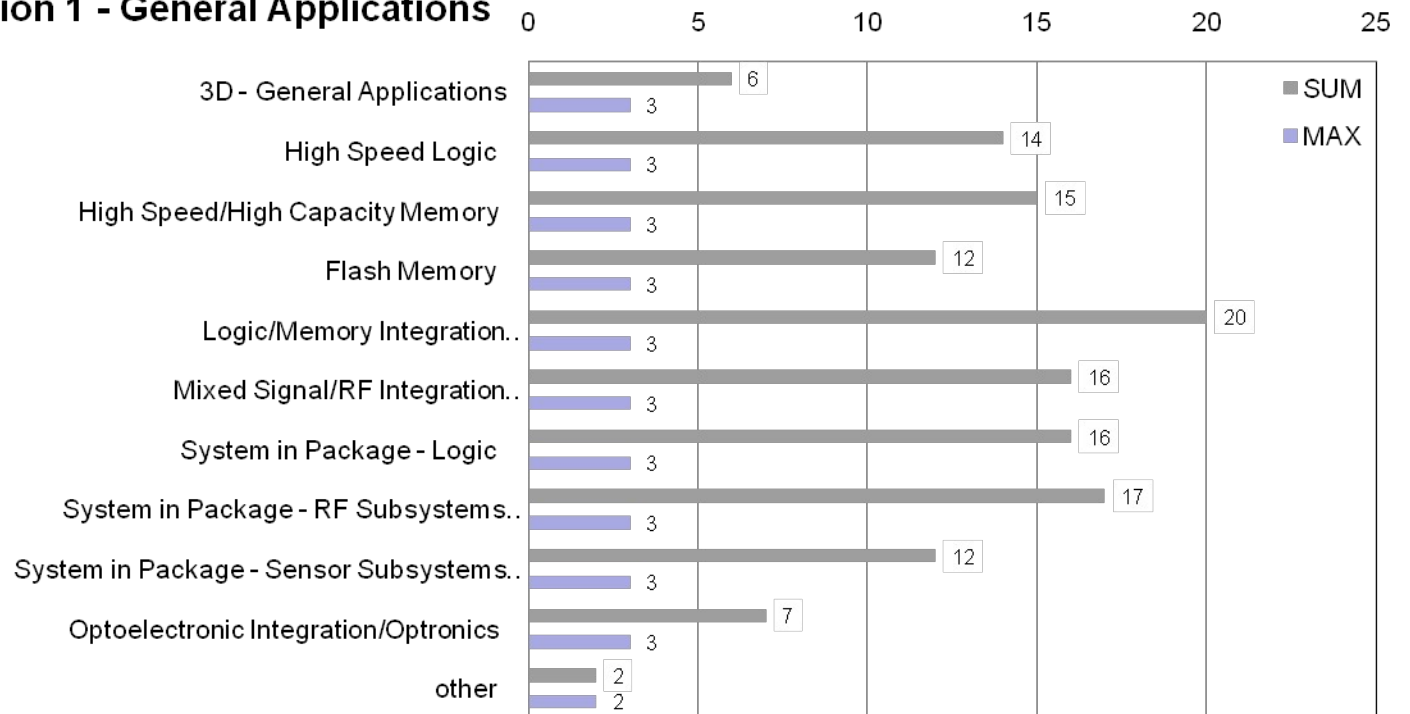
- SiP Embedded die 2008 -
  - Demonstrator
  - Technology Reviews
- 3D SiP Questionnaire v2
  - 9 replies as of Feb 18
  - Sharing points of interest
  - Additionally lots of comments
- Today choose topics and project drafts: Test Vehicle / Demonstrator??

Next up:

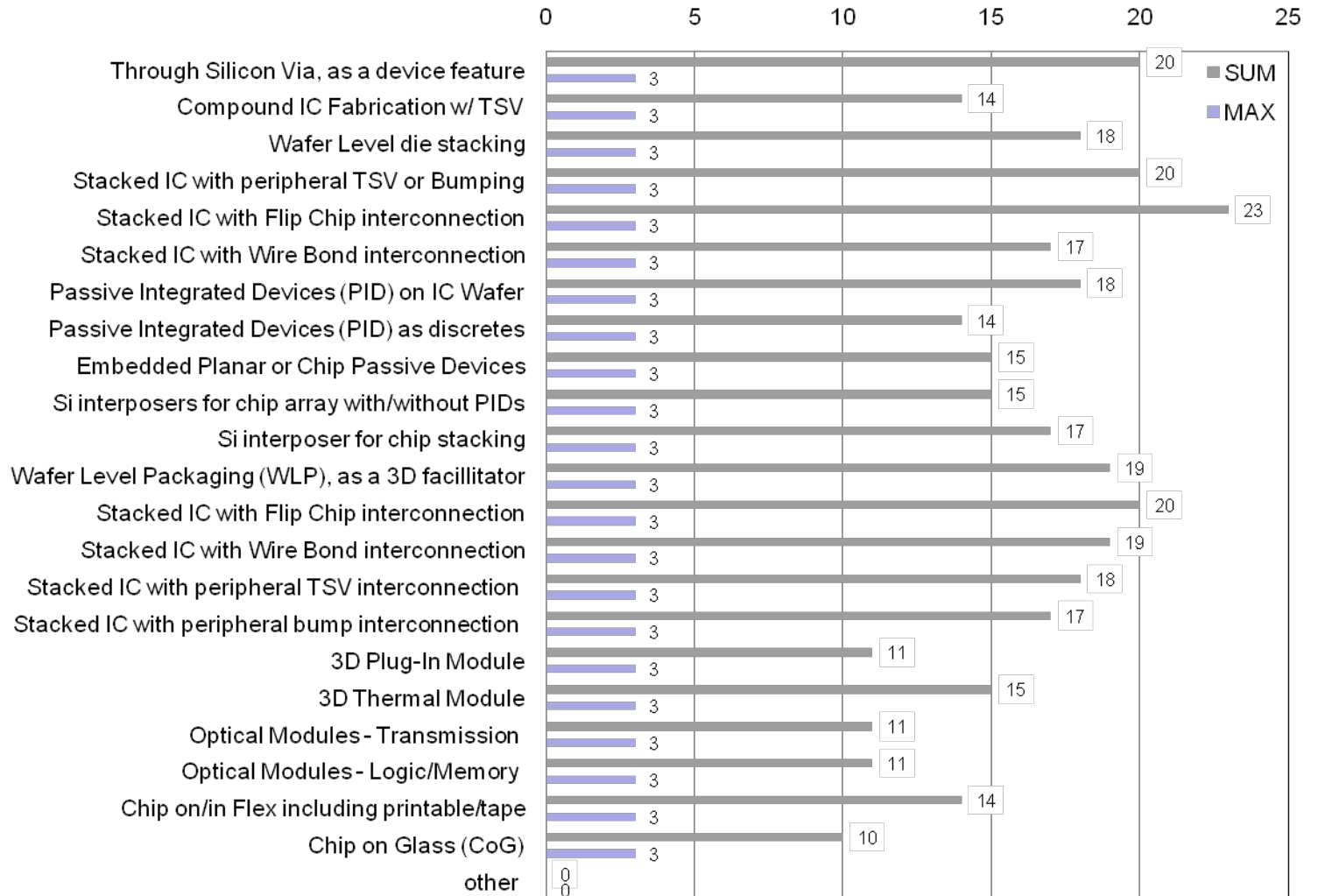


- Introduction to the topic area to be covered by Chris Katzko, project leader, Meadville
- Company views by two invited member company representatives Bernd Appelt, ASE and others

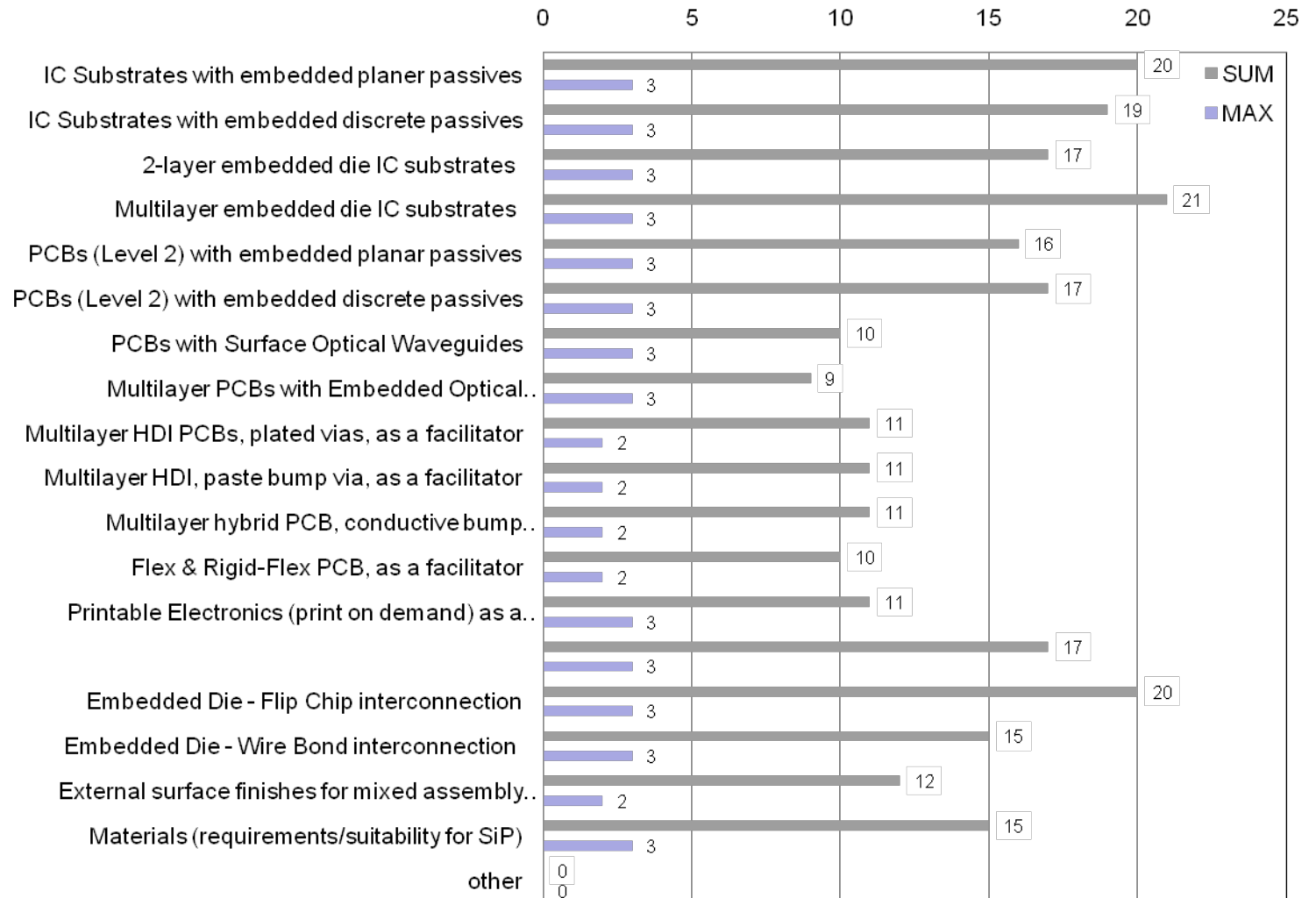
## Section 1 - General Applications



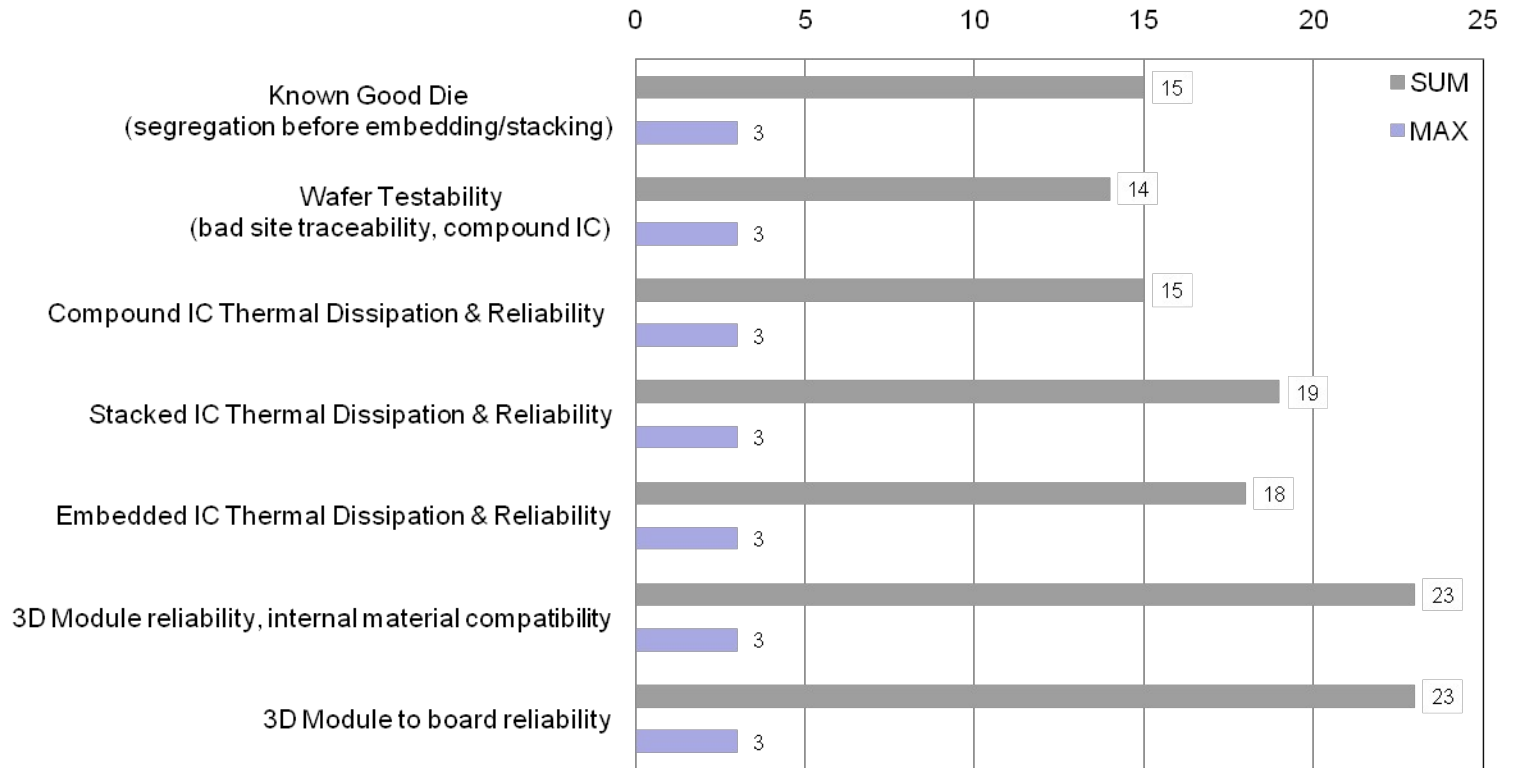
## Section 2 - IC Fab, Back-End Process & Packaging



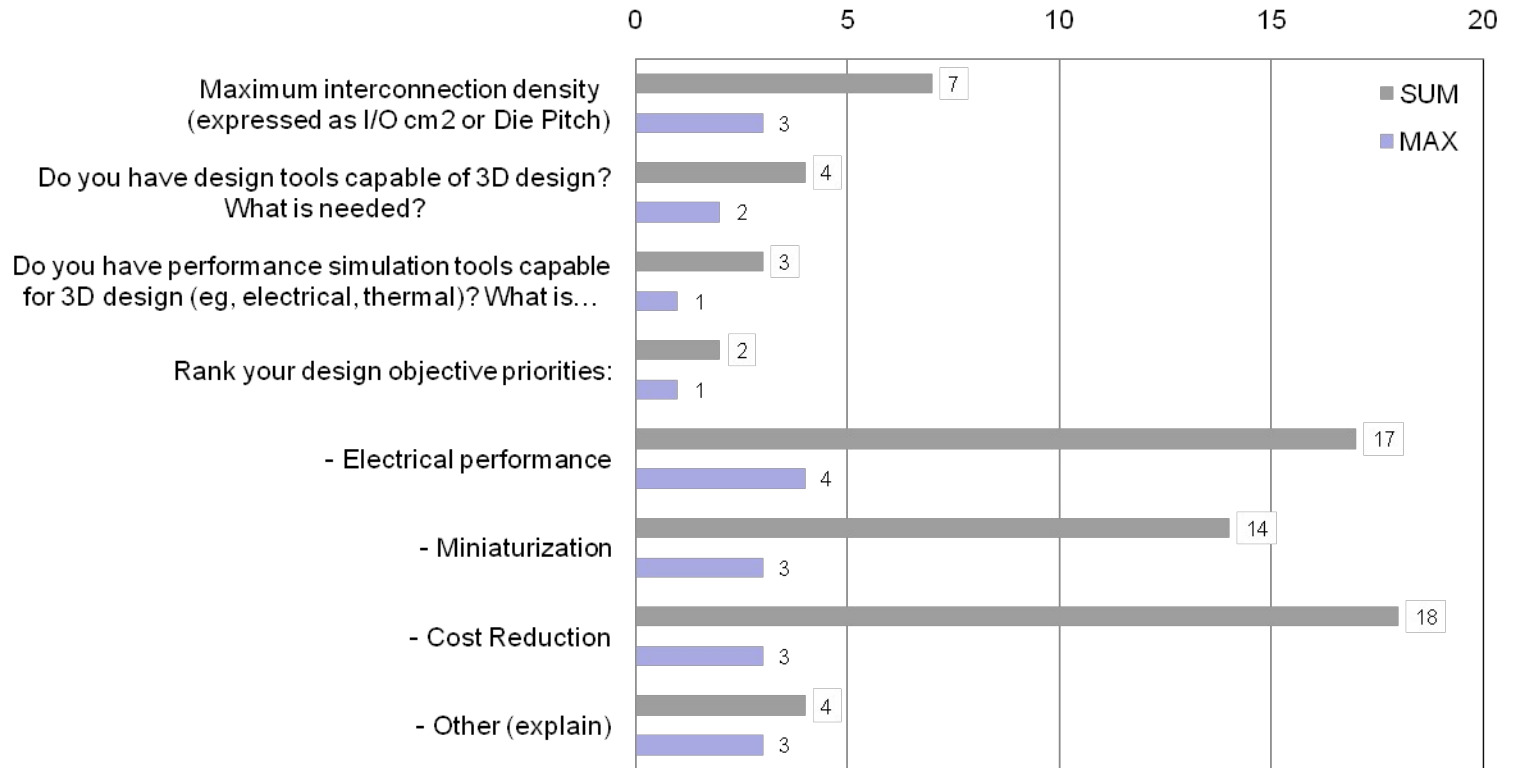
## Section 3 - IC Substrate & PCB Technology



## Section 4 - Testability, Reliability & Performance



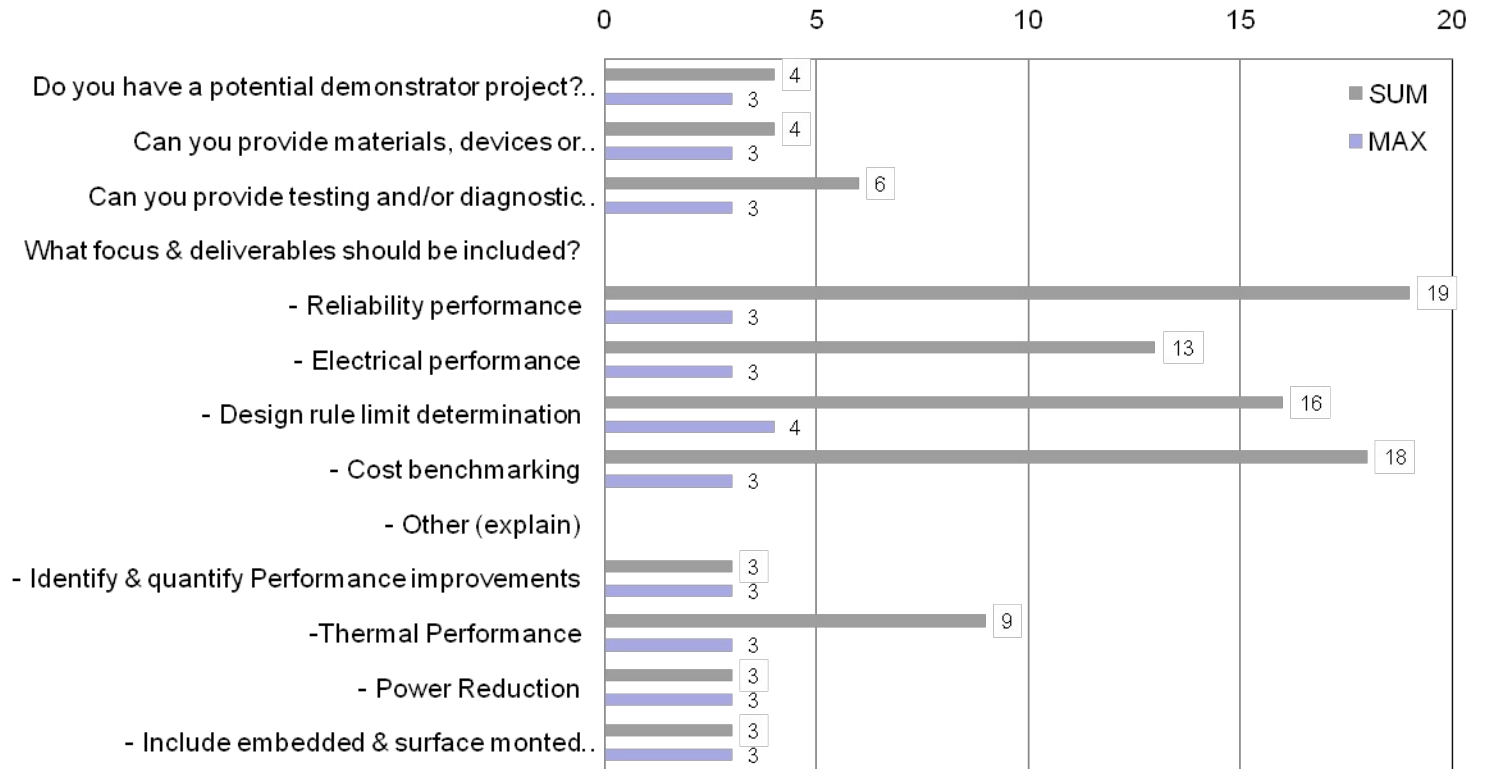
## Section 5 - Design Issues



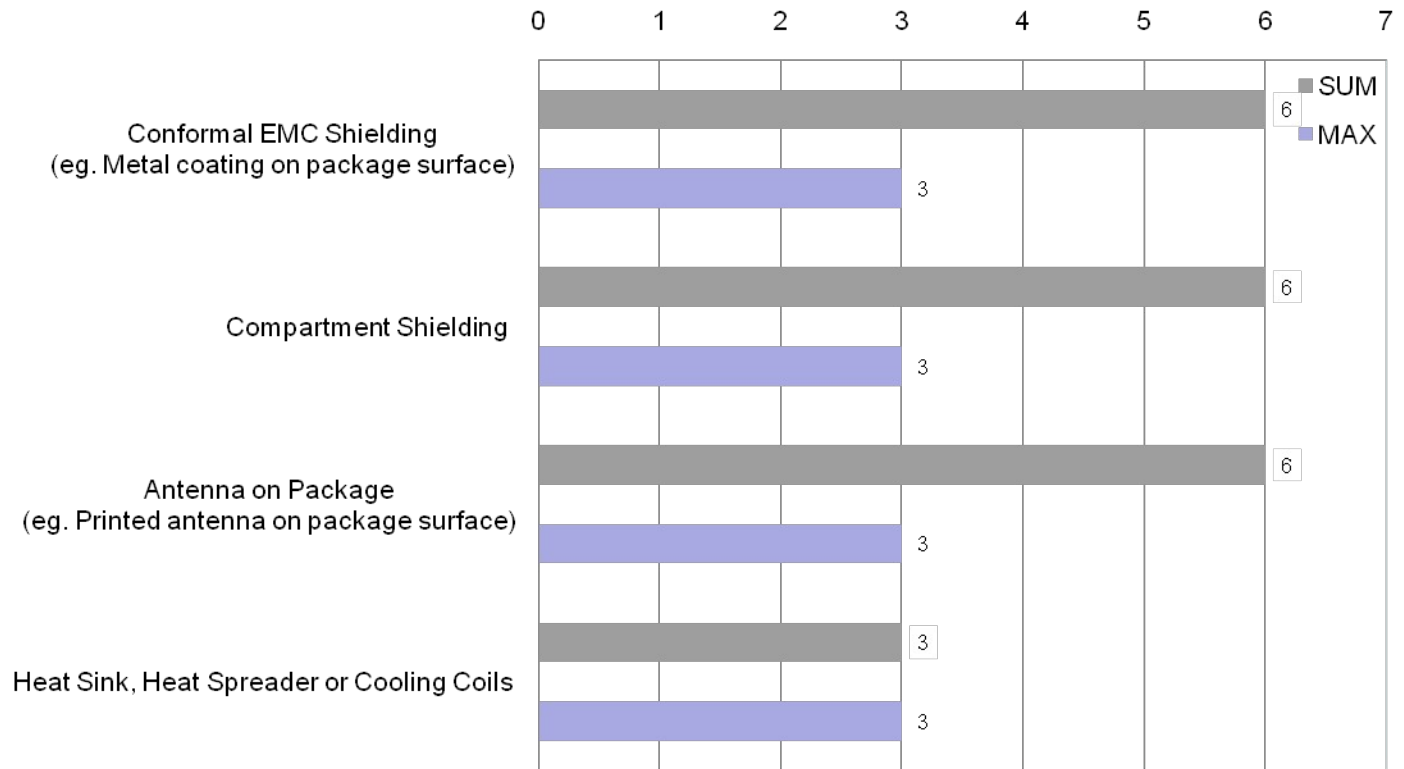
# Demonstrator Project Support



## Section 6 - Demonstrator Project Support



## Section 7 - Other Topics



Next up:



- List of identified issues suitable for technology assessment, demonstrations and/or reliability assessment (Chris)
- Discussion on priorities in this list
- Brainstorming for additional issues to be worked on
- Formulate maximum 5 project ideas based on discussion so far: Technical coverage & Goals & Volunteers
- Voting on these 5 ideas, 1 or 2 to be flashed at Member Meeting next day
- How to proceed? Formation of top teams